

Amendments to the Specification

Please rewrite paragraph [0080] to read as follows:

[0080] A polymer attracting device may also be provided to lead polymer, being away from the monitoring window. Preferably, the polymer attracting device is disposed at the fringe of the monitoring window. Preferably, a liner covers the polymer ~~leading part~~ attracting device to make the removal of the polymer therefrom easy. The polymer attracting device may comprise an electrostatic unit for generating a constant electrostatic force and/or a cooling unit for creating an atmosphere within the chamber that is lower than that typically prevailing during the plasma etching process.

Please rewrite paragraph [0100] to read as follows:

[0100] However, as shown in FIG. 3, the monitoring window 20 is provided with a flute 22 ~~that~~ at an inner portion thereof facing into the chamber 12. The flute ~~20~~ 22 has a certain depth as taken in an outward direction with respect to the chamber 12. The monitoring window 20 is also provided with a protrusion 26 at an outer side thereof and which protrusion 26 extends in the outward direction. The flute 22 may be so deep as to reach the innermost end of the protrusion 26.

Please rewrite paragraph [0125] to read as follows:

[0125] The polymer attracting device 28 can be an electrostatic device, a cooling unit or a combination thereof. In the case of the electrostatic device, the device generates an electrostatic force by power supplied thereto under the control of the controller so as to attract the polymer onto a surface thereof or onto the liner 30. The cooling unit forms a temperature atmosphere lower than the interior temperature of the chamber 12, which makes the polymer more likely to adhere thereto than to other high-temperature portions adjacent to the unit, such as the monitoring window 20. Note, the controller can be configured to drive the polymer attracting device 28 at the time the etching process is completed so that the operation of the polymer attracting ~~part~~ device 28 does not ~~influencees~~ influence the etching process. On the other hand, the heater 24 is operated continuously during the etching process to prevent the flute 22 and the monitoring window from being polluted by polymer during the process.